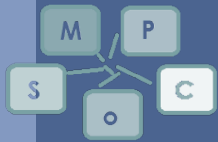


HiPAcc-LTE: An Integrated High Performance Accelerator for 3GPP LTE Stream Ciphers

Sourav Sen Gupta¹, Anupam Chattopadhyay², Ayesha Khalid²

1. *Applied Statistics Unit, Indian Statistical Institute, Kolkata, India*

2. *MPSoC Architectures, UMIC Lab, RWTH Aachen, Germany*

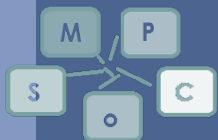


Outline of the Talk

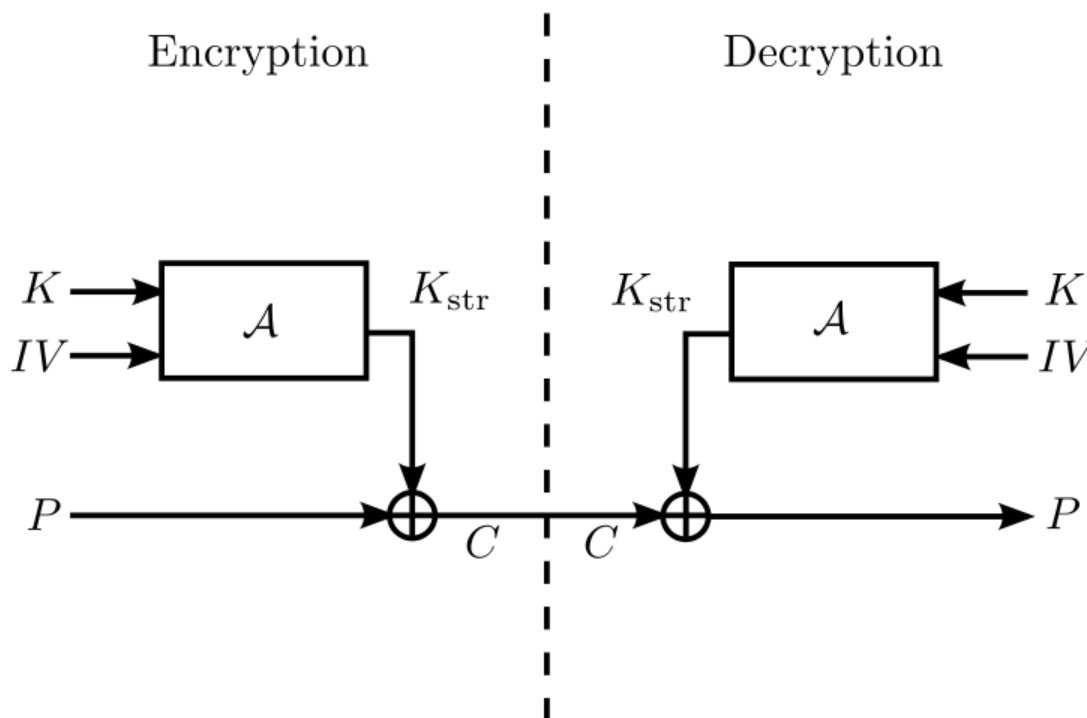


Motivation and Preliminaries

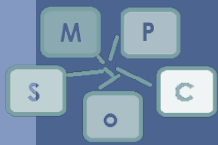
- Design of Integrated Accelerator HiPAcc-LTE
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Hardware for Stream Ciphers



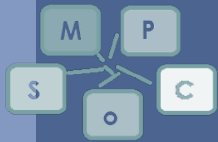
- **Enhance hardware performance of existing designs**
 - Dedicated hardware modules for high speed and low area
- **New designs targeted towards hardware performance**
 - eSTREAM profile 2 (HW): Grain v1, MICKEY v2, Trivium



Our Motivation

- **Enhance hardware performance of existing designs**
- **The general trend**
 - Standalone modules for individual ciphers (eSTREAM)
 - Few different ciphers put into a single package (HSMs)
- **The path not charted**
 - Fuse multiple designs together before implementation
 - Algorithm-level merger for ciphers with similar structure
 - Single base framework, rather than a package

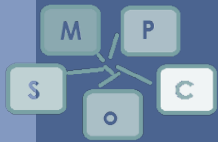
If there is a requirement to implement an array of ciphers on the same platform, how should one approach the hardware design?



Case Study



- **3GPP LTE Advanced – Security Suite**
 - EEA1/EIA1 – based on SNOW 3G (same as in 3G)
 - EEA2/EIA2 – based on AES-128 (changed from KASUMI)
 - EEA3/EIA3 – based on ZUC (brand new inclusion)
- **Observation**
 - Two similar stream ciphers in the same package
 - In general, only one will be used at any given time



Goal of the Project

3GPP LTE Advanced Security Module

HiPAcc-LTE

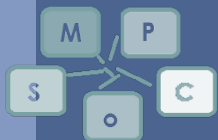
SNOW 3G + ZUC

+

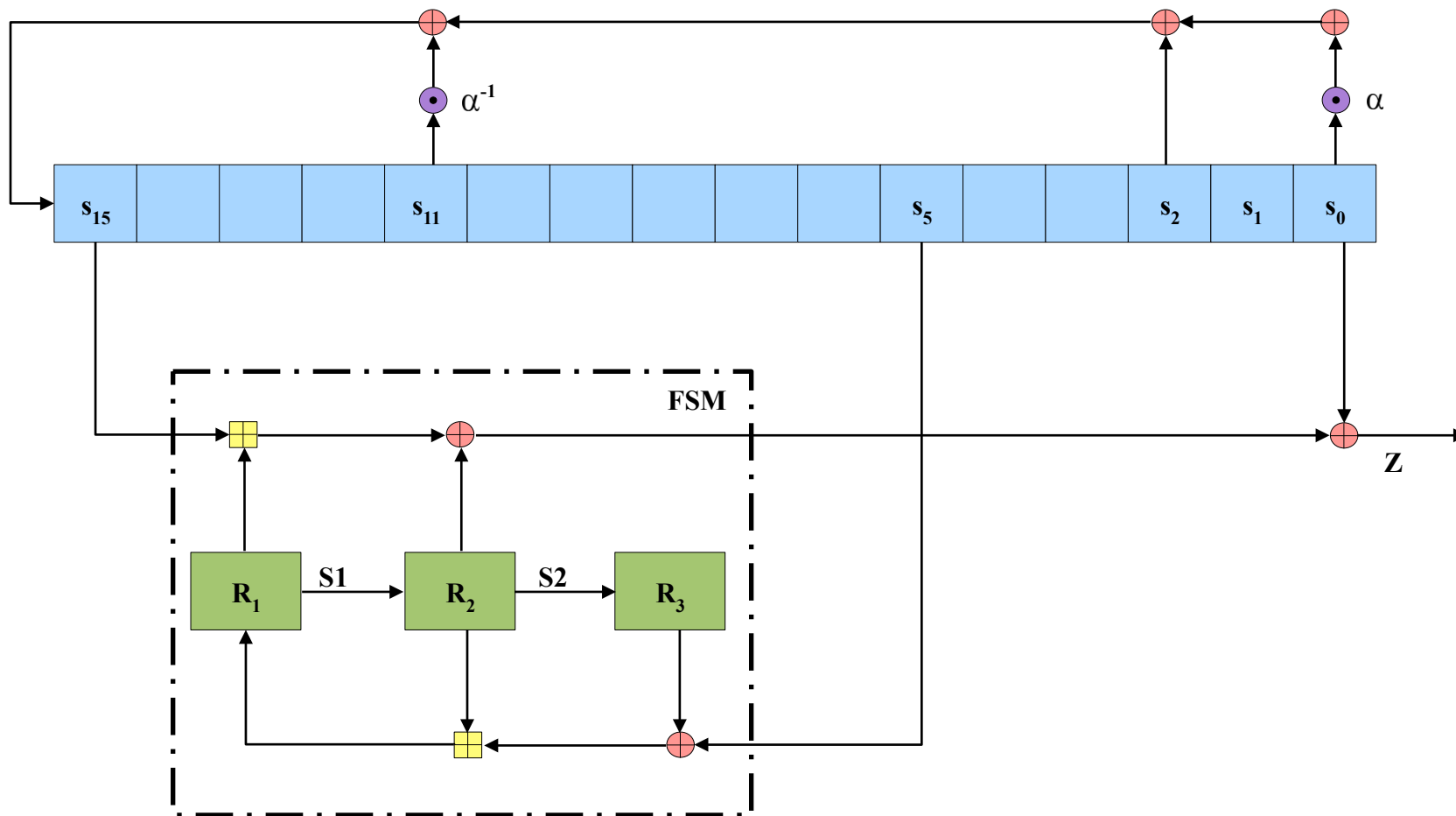
StandaloneCore

AES-128

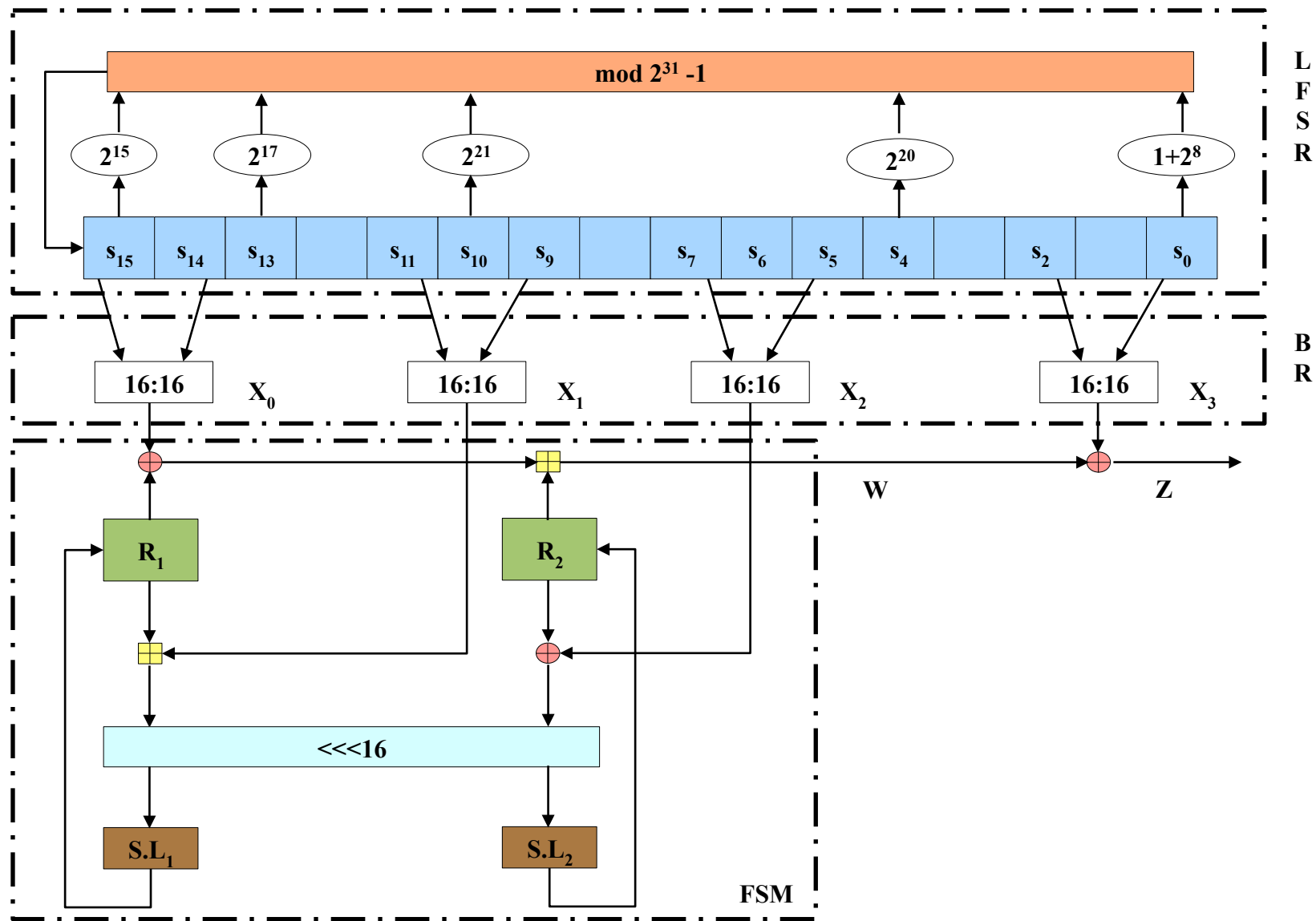
- **Fuse SNOW 3G and ZUC in hardware**
 - Sharing of resources, both storage and logic
 - Throughput vs. area optimization at the base level
- **HiPAcc-LTE: Integrated platform**
 - Integrate similarities of the individual designs
 - Push the performance (speed and area) for both

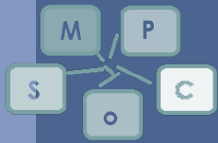


Preliminaries - SNOW 3G



Preliminaries - ZUC





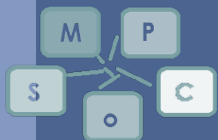
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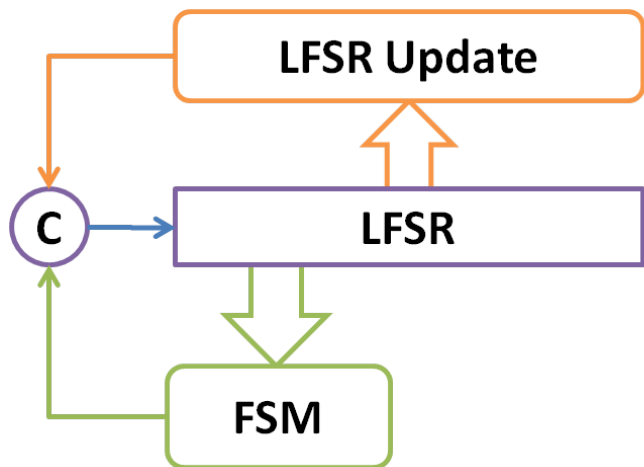


Design of Integrated Accelerator HiPAcc-LTE

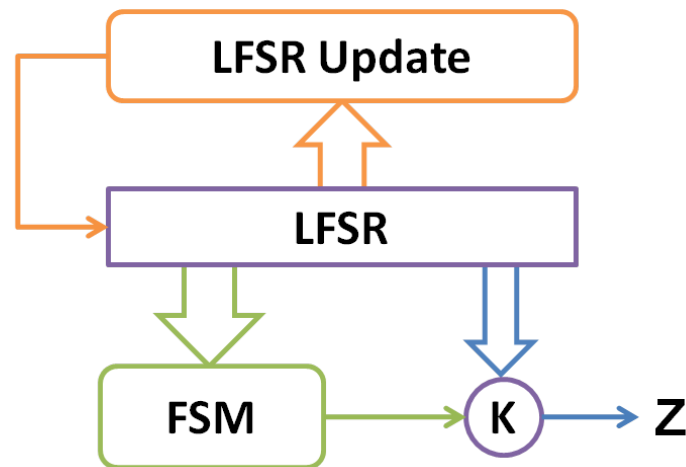
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Scope for Integration



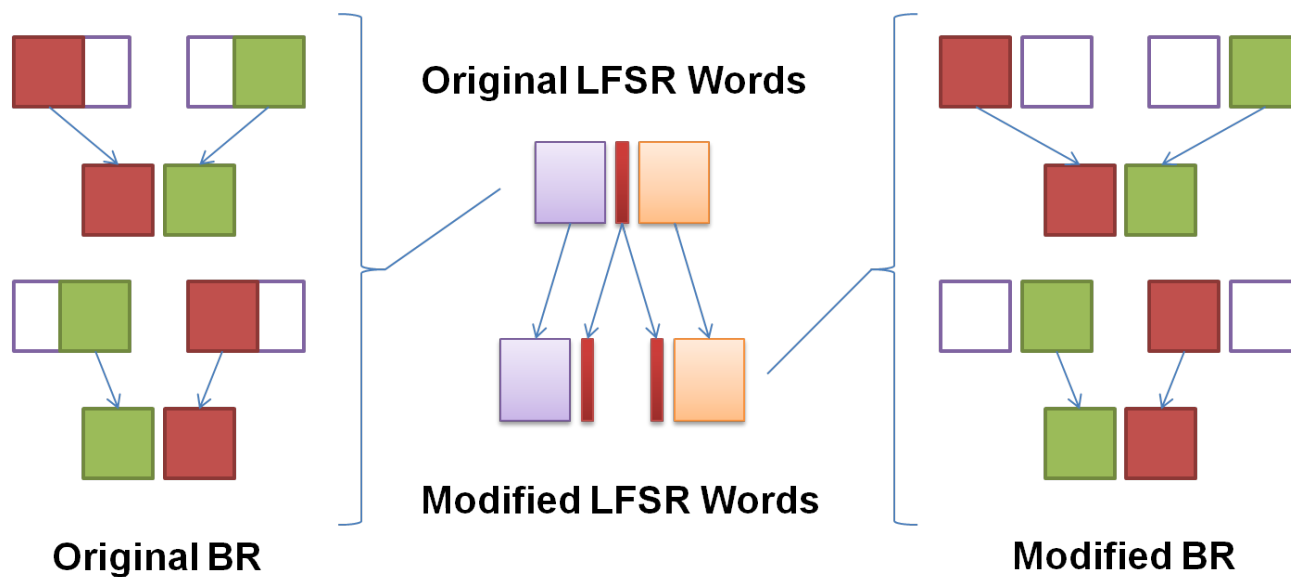
Initialization Mode



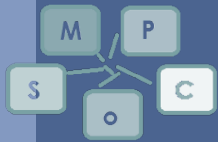
Keystream Generation Mode

Cipher	LFSR Update	LFSR	FSM
SNOW 3G	Field Mul/Div and XOR	32 bits x 16	3 Registers and 2 S-boxes
ZUC	Modulo prime addition	31 bits x 16	2 Registers and 2 (S.L)-boxes

- **Use 16 bits x 32 LFSR structure for both**
 - SNOW 3G – just break the 32 bit blocks into halves
 - ZUC – 1 bit extra per 32 bits – duplicate the middle bit



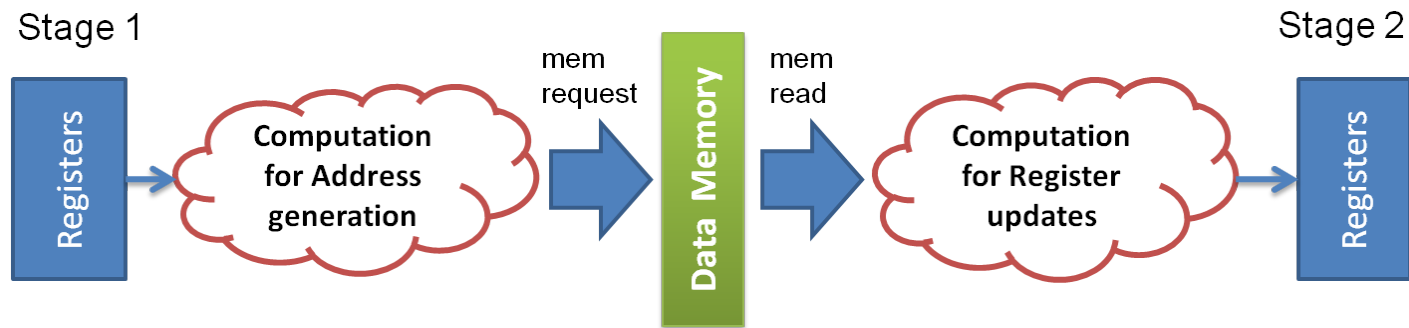
- **BR layer moved to LFSR update from FSM operation**
 - Reduces the critical path that flows through the FSM
 - Causes no significant disadvantage in LFSR update routine



Designing the Pipeline – FSM

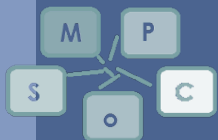
- **Store S-box and Mul/Div-alpha tables in Memory**
 - Allow for memory request and read time
 - Share resources: 2 registers and 8 memory tables

- **Initial design**



- **Final design**

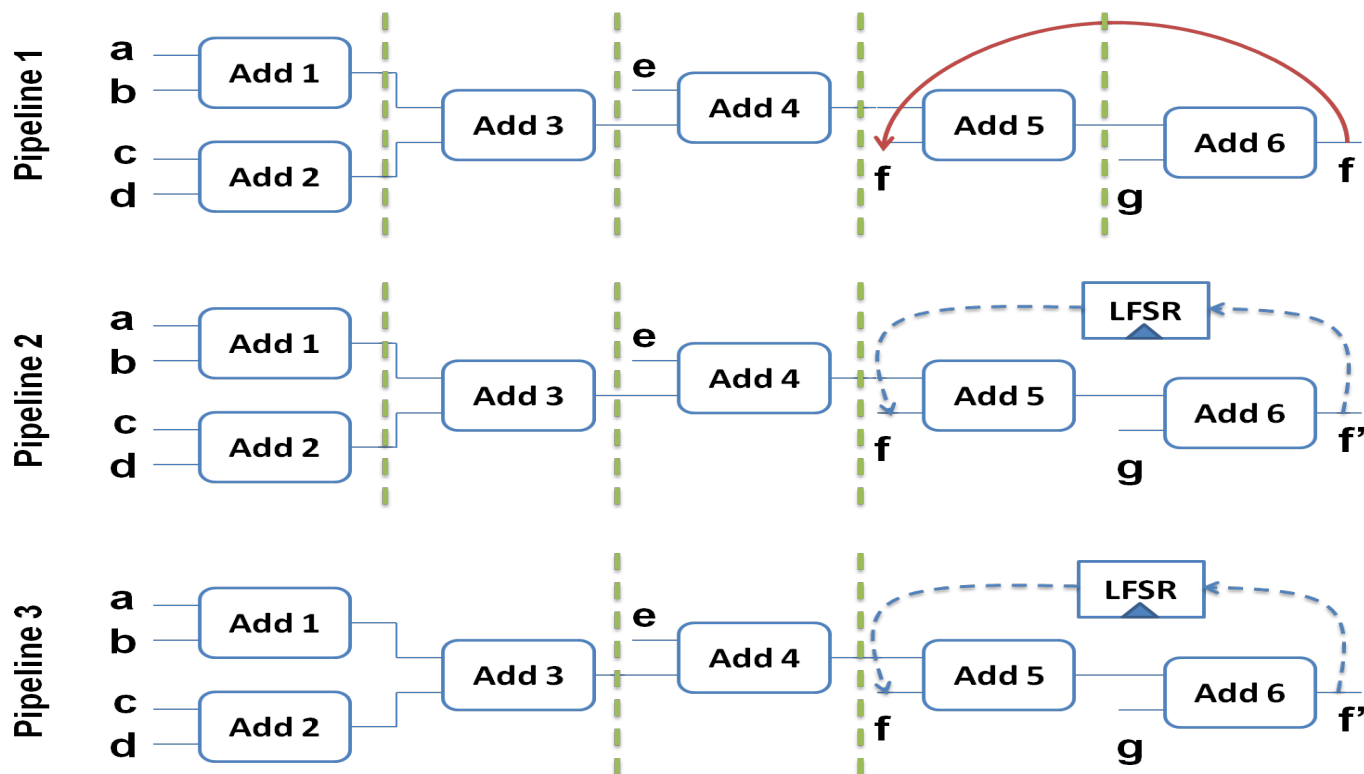
- Just precomputation at the first stage
- Memory request moved to the end of second stage



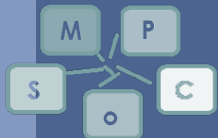
Designing the Pipeline – LFSR

- ZUC – 6 modulo prime additions for the update

$$s_{16} = s_0 + 2^8 s_0 + 2^{20} s_4 + 2^{21} s_{10} + 2^{17} s_{13} + 2^{15} s_{15} \pmod{2^{31} - 1}$$

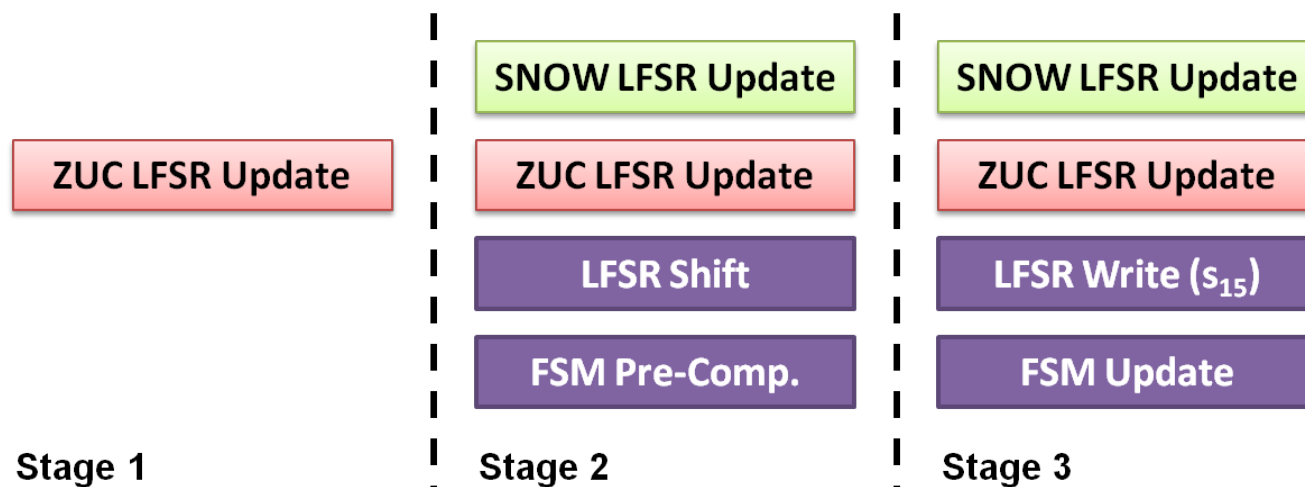


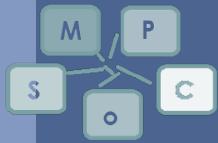
- SNOW 3G – 3 simple XORs; fits into the same structure



Final Pipeline Structure

- **FSM: Two stages**
 - initial computations for address generation in the first stage
 - memory access and related computations in the second stage
- **LFSR Movement: Two stages**
 - shift in first stage and s_{15} write in second stage
- **LFSR Update: Two/Three stages**





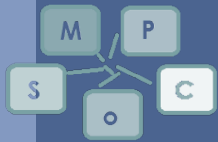
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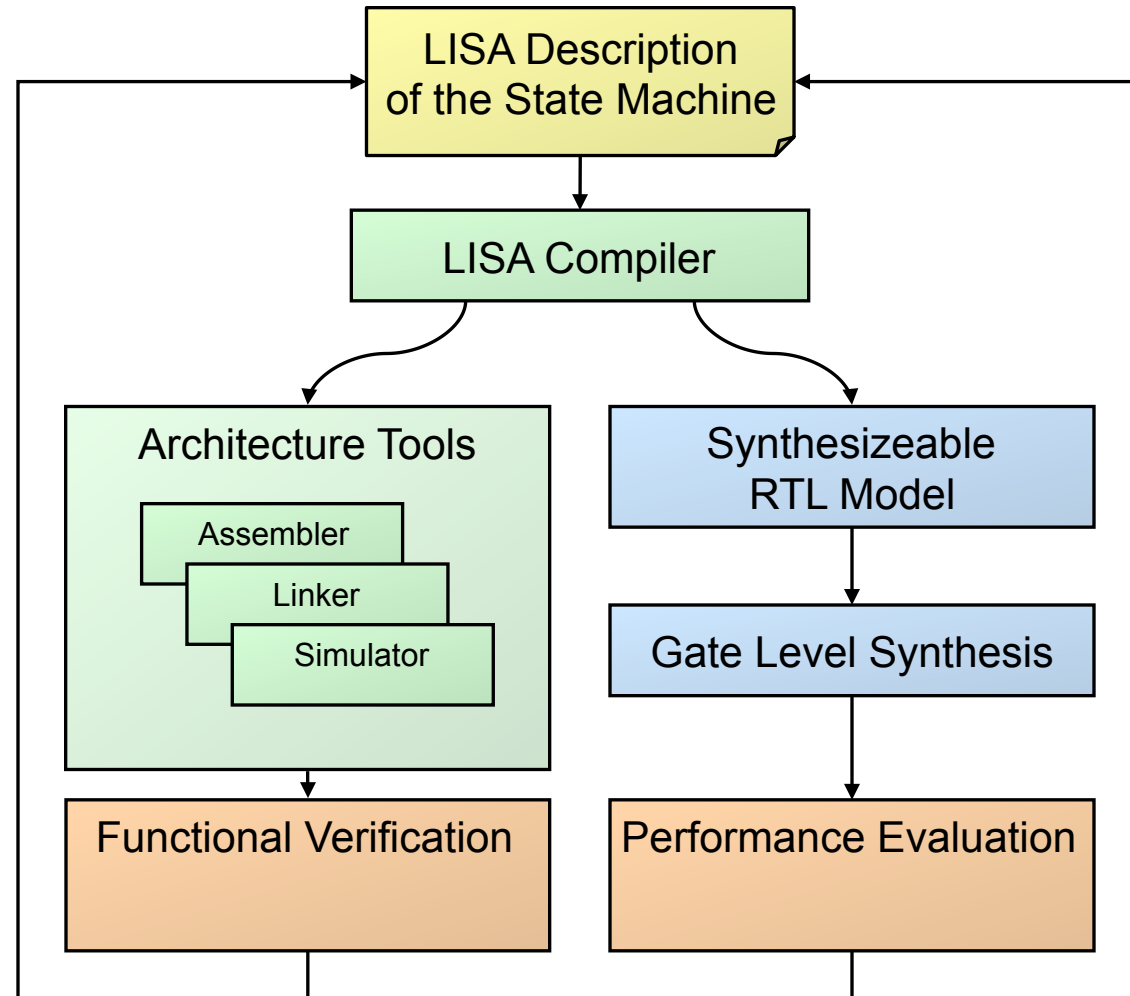


Implementation and Experimental Results

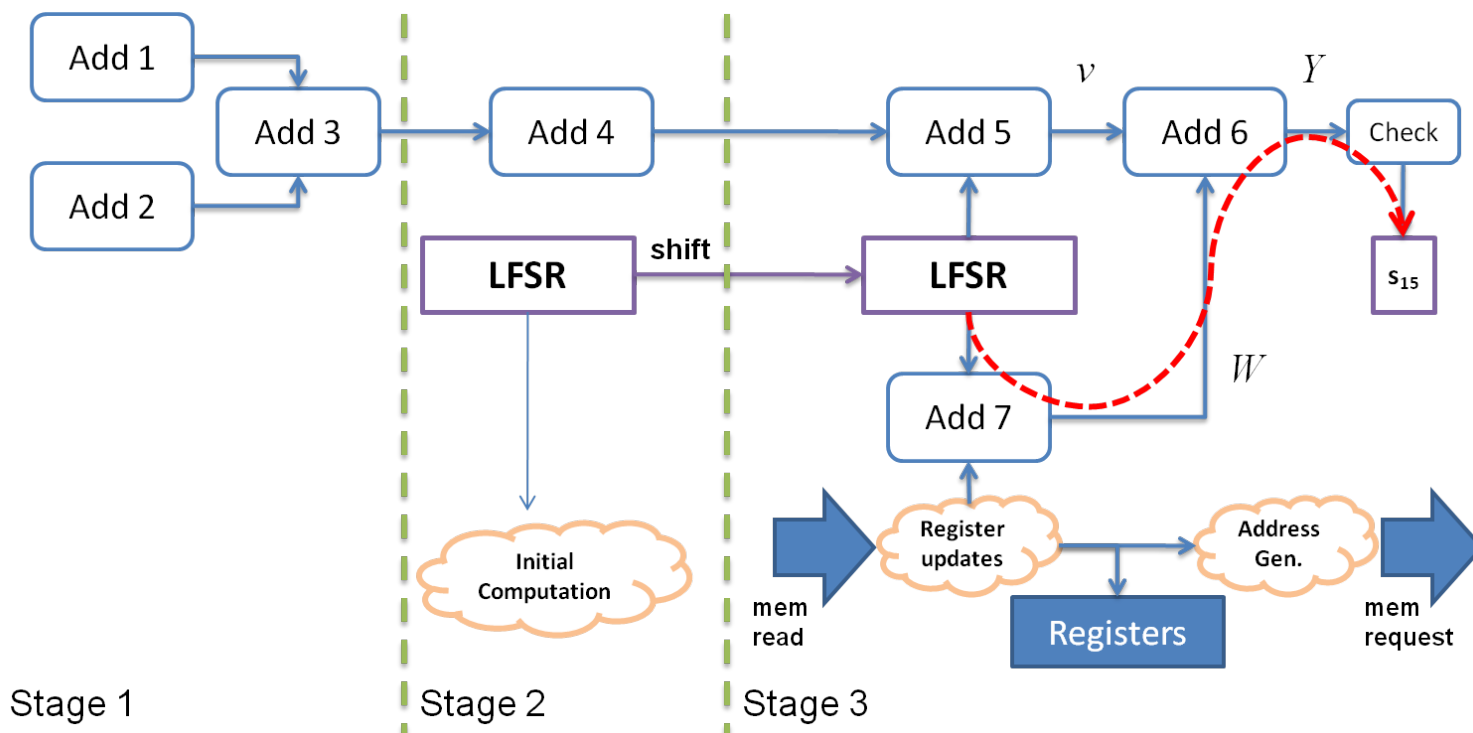
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High-Level Design Flow



- After the initial synthesis: In ZUC Key Initialization



LFSR Key Initialization (W)

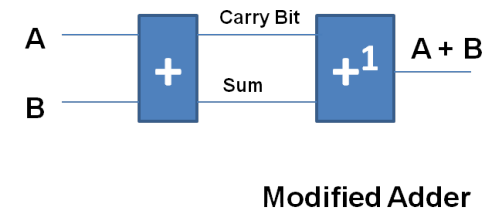
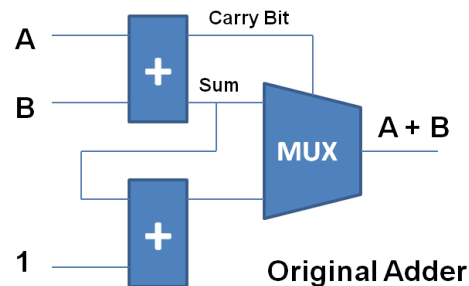
- $v = 2^{15}s_{15} + 2^{17}s_{13} + 2^{21}s_{10} + 2^{20}s_4 + 2^8s_0 + s_0 \pmod{2^{31} - 1}$
- $Y = v + (W \gg 1) \pmod{2^{31} - 1}$
- If $Y = 0$, then set $Y = 2^{31} - 1$
- Write Y to location s_{15} of the LFSR

- **LFSR read optimization**

- Original: Register array – access from different stages in pipeline
- Optimized: 32 distinct 16-bit registers – placed independently

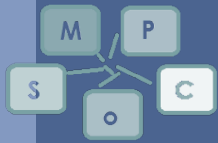
- **Modulo prime adder optimization**

- Original: A layer of multiplexer in series with adder and increment
- Optimized: Just increment the first adder output by the carry bit

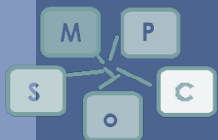


- **Check optimization**

- Original: Check if $Y = 0$ where $Y = v + (W \gg 1) \bmod 2^{31} - 1$
- Optimized: Note that Y can never be 0 for proper v and W



- **Standalone modes for SNOW 3G and ZUC**
 - **Academic literature** – generally 130 nm technology
SNOW 3G: Kitsos et al, IFIP/IEEE VLSI-SOC '08
ZUC: no attempt in ASIC till date
 - **Commercial designs** – generally 90, 65 nm technology
SNOW 3G: IP Cores Inc., SNOW3G1 core
ZUC: Elliptic Tech. Inc., CLP-410 core
- **Integrated mode of HiPAcc-LTE**



Performance – Standalone SNOW 3G

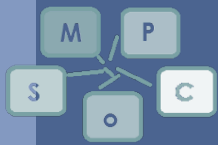
Comparison in 130 nm technology - Academic

Design	Designer	Throughput	Area	Memory
SNOW 3G	Kitsos et al	7.97 Gbps	25 Kgate	10 Kbyte
HiPAcc-LTE	- - -	24.0 Gbps	18 Kgate	10 Kbyte

Comparison in 65 nm technology - Commercial

Design	Designer	Throughput	Area	Memory
SNOW3G1	IP Cores Inc.	7.5 Gbps	8.9 Kgate	Hard Macro
HiPAcc-LTE	- - -	32.0 Gbps	7.0 Kgate	3 Kbyte
HiPAcc-LTE	- - -	52.8 Gbps	18 Kgate	Hard Macro

gate level synthesis results are obtained using Faraday 130, 90, 65 nm technology, best case performance using Synopsys DC topographical mode

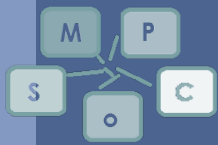


Performance – Standalone ZUC

Comparison in 65 nm technology - Commercial

Design	Designer	Throughput	Area	Memory
CLP-410	Elliptic Tech	16.0 Gbps	10-13 Kgate	Hard Macro
HiPAcc-LTE	- - -	32.0 Gbps	11 Kgate	3 Kbyte
HiPAcc-LTE	- - -	29.4 Gbps	20.6 Kgate	Hard Macro

gate level synthesis results are obtained using Faraday 130, 90, 65 nm technology, best case performance using Synopsys DC topographical mode



Performance – Integrated Design

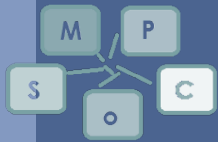
Performance figures for both ciphers together – 65 nm technology

Design	Frequency	Throughput	Area	Memory
HiPAcc-LTE	1090 MHz	34.88 Gbps	17 Kgate	10 Kbyte
HiPAcc-LTE	1090 MHz	34.88 Gbps	17 Kgate	3 Kbyte
HiPAcc-LTE	920 MHz	29.4 Gbps	24 Kgate	Hard Macro

Comparison in 65 nm technology - Commercial

Design	Designer	Throughput	Area	Units reqd.
SNOW3G1	IP Cores Inc.	7.5 Gbps	8.9 Kgate	4
CLP-410	Elliptic Tech	16.0 Gbps	10-13 Kgate	2
Combined	Both	30-32 Gbps	56-62 Kgate	1
HiPAcc-LTE	- - -	29.4 Gbps	24 Kgate	1

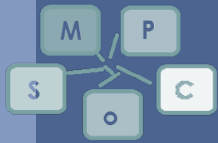
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■ Summary

- Multiple designs are proposed to serve similar purpose
 - varying degree of security
 - minor design choice variation
 - non-technical reasons
- Integrated design offers significant performance improvement
- Case study with 3GPP LTE stream ciphers presented here

■ Long term vision

- Design of a flexible core supporting multiple ciphers
- Intermediate design points for individual algorithms
- Unified platform with optimal performance for various ciphers

Thank You

